

1.09mm (.043") by 1.17mm (.046") Pitch LGA Socket 771

Molex offers the 771-pin LGA CPU Socket for the Intel Dempsey Platform Processor

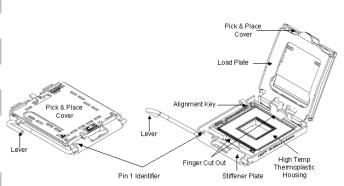
Socket 771 is the first Computer Processing Unit (CPU) socket to be used on the server/workstation industry featuring the Land Grid Array (LGA) contact design. This socket is commonly known as Socket J, Socket 771 and LGA 771. This socket mates with the 771 LGA CPU package (gold pads) to form the processing unit of the application. Previous design uses the Pin Grid Array (PGA) socket or Micro-PGA socket (such as socket 604) mated with PGA CPU package. The 771-pin LGA CPU and Socket will replace the Socket 604 in Intel®Xeon® processor line.

Molex's high density LGA sockets features our low profile design, the shepard hook actuation lever and a flat or raised pick and place cover for the assembly process. All Molex's LGA sockets comes with lead or lead-free BGA solder balls.

Features	Benefits
High-temperature thermoplastic housing	Withstands lead-free processing
Pick-&-place cover and Jedec hard packaging tray	Facilitates automation socket placement
• LGA contact/BGA solder	• Prevents CPU misalignment
• Lead free BGA solder balls	• Compliant with environmental needs
Shepard hook actuation lever	• For easy actuation
• Flat or raised pick & place cover	• Raised cover facilitates easy removal
 Visible triangle pin 1 identification on housing, pick & place cover, stiffener plate. 	• Ensure correct CPU loading
• West alignment key.	 Prevent Socket 775 CPU from mating to socket 771.
• 2 finger cutouts on north and south	• For oney CPII romoval

For easy CPU removal





SPECIFICATIONS

side

Reference Information

Packaging: JEDEC Thick Handling Hard Tray

UL File No.: E29179

Mates With: Intel®Xeon® Processor family(771-pin Package)

Designed In: Millimeters

Electrical
Voltage: 30V
Current: 0.8A

Contact Resistance: 15.2 milliohms max. average,

28.0 milliohms max. chain

Dielectric Withstanding Voltage: 360V AC Insulation Resistance: 500 Megohms min.

Mechanical

Insertion Force to Socket: Zero Insertion Force

Durability: 20 cycles

Physical

Housing: LCP, UL 94V-0 Contact: Copper Alloy

Plating:

Contact Area — 0.38 um (15u") Gold

Solder Tail Area — Underplating — Nickel

Operating Temperature: -40 to +90°C

MARKETS AND APPLICATIONS



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Workstation/Low End Server



Vertical Surface Mount





ORDERING INFORMATION

Lead-Free Order No.	Tin-Lead Order No.	Description
47213-0015	47213-0010	1.09mm (.043") by 1.17mm (.046") Pitch LGA Socket, 771 Circuits, 15u" Gold Plating, Shepherd Hook Lever, Flat Pick & Place Cover
47213-1015	47213-1010	1.09mm (.043") by 1.17mm (.046") Pitch LGA Socket, 771 Circuits, 15u" Gold Plating, Shepherd Hook Lever, Raised Pick & Place Cover
47213-0005	47213-0000	1.09mm (.043") by 1.17mm (.046") Pitch LGA Socket, 771 Circuits, 30u" Gold Plating, Shepherd Hook Lever, Raised Pick & Place Cover

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